IAPO1Rec'd PCT 09 SEP 2010

FORM PTO-1596 1-31-92	HEI-065 3-2010			
1-31-92	U.S. DEPARTMENT OF COMMER 40 /7 7 Pcnt CT Cent O			
To the Honorable Commissioner of P 103				
	606611 original documents or copy thereto:			
1. Name of conveying party(ies):	2. Name and address of receiving party(ies):			
 Atsushi YONEDA Yuuji IWAKIRI 	Name: TOYO SEIKAN KAISHA, LTD. Street Address: 3-1, Uchisaiwaicho 1-chome, City: Chiyoda-ku, State: Tokyo Zip: 100-8522			
3. Nature of conveyance:	Country: Japan			
☑ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other				
Execution Date: July 20 & 16, 2010	Additional name(s) & address(es) attached? ☐ Yes ☒ No			
If the document is being filed together with a new application, A. Patent Application No(s). New Application - Not yet assigned	B. Patent No(s). (PATENT» «ISSUED»			
Additional numbers	attached? Yes X No			
Name and address of party to whom correspondence concerning document should be mailed: Name: KANESAKA BERNER & PARTNERS	 6. Total number of applications and patents involved: one 7. Total fee (37 CFR 3.41).\$			
PATENT AGENTS, LLP	☐ Authorized to be charged to deposit account			
Internal Address:	☐ Credit Card payment form enclosed			
Street Address: 1700 Diagonal Road, Suite 310	8. Deposit account number:			
City: Alexandria State: VA Zip: 22314				
DO NOT U	SE THIS SPACE			
9. Signature. Manabu Kanesaka, No. 31,467 Name of Person, Registration No.	Signature Date			
Total number of pages including cover sheet, attachment, and document:	Total number of pages including cover sheet, attachme and document:			

09/10/2010 LLANDGRA 00000018 12736088

05 FC:8021

40.00 OP

REEL: 024972 FRAME: 0908

MP01Rec'd PCT_09 SEP 2010

12/736088

ASSIGNMENT

For value received, we, Atsushi YONEDA and Yuuji IWAKIRI
having post office address/residing at
c/o TOYO SEIKAN KAISHA, LTD., TECHNOLOGY & PACKAGING DEVELOPMENT
DIVISION, 1-1-70, Yako, Tsurumi-ku, Yokohama-shi, Kanagawa
230-0001 Japan
hereby sell, assign and transfer to TOYO SEIKAN KAISHA, LTD.
a corporation existing under the laws of located at
3-1, Uchisaiwaicho 1-chome, Chiyoda-ku, Tokyo 100-8522 Japan
and its successors, assigns, and legal representatives the entire right,
title, and interest for all countries including the United States of
America, in and to certain inventions relating to
MOLDING METHOD, MOLTEN RESIN COMPRESSION MOLDING DEVICE, AND SYNTHETIC RESIN
CONTAINER MANUFACTURING METHOD
described in application for Letters Patent of the United States,
executed by me/us on this date, and all patents which may be granted
therefor, and all divisions, reissues, continuations and extensions
thereof, and authorize and request the Commissioner of Patents and
Trademarks to issue all patents on said improvements or resulting
therefrom to said Company as assignee of the entire interest, and
covenant that I/We have full right so to do, and agree that I/We will
communicate to said Company or its representatives any facts known to
me/us respecting said improvements and testify in any legal proceedings,
sign all lawful papers, execute all divisional, continuing and reissue
applications, make all rightful oaths and generally do everything
noscible to aid said Company its successors assigns and nominees

Page 1 of 2

REEL: 024972 FRAME: 0909

Jeaces.						
Signature	Atsushi You (Name) Atsushi YONEDA	neda	Date	July.	20.20/	<u>0</u>
Signature _.	YUUJI I (Name) Yuuji IWAKIRI	wakiri	Date	July.	16. 201	<u>'0</u>
Signature _.	(Name)		Date			
Signature _,	(Name)		Date			
Signature	(Name)		Date			

to obtain and enforce proper protection for said invention in the United

Page 2 of 2

Signature _____ Date_____

PATENT REEL: 024972 FRAME: 0910

RECORDED: 09/09/2010